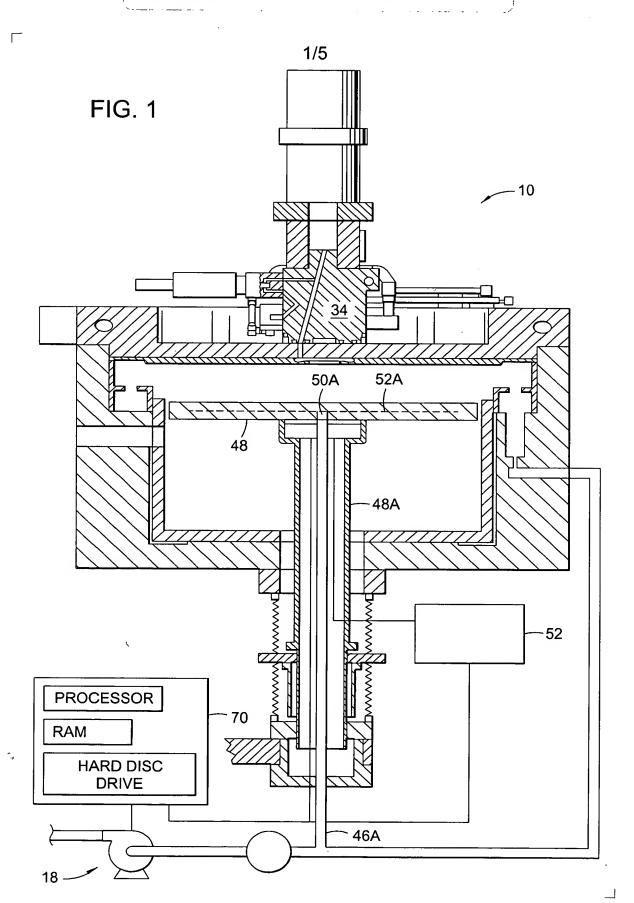
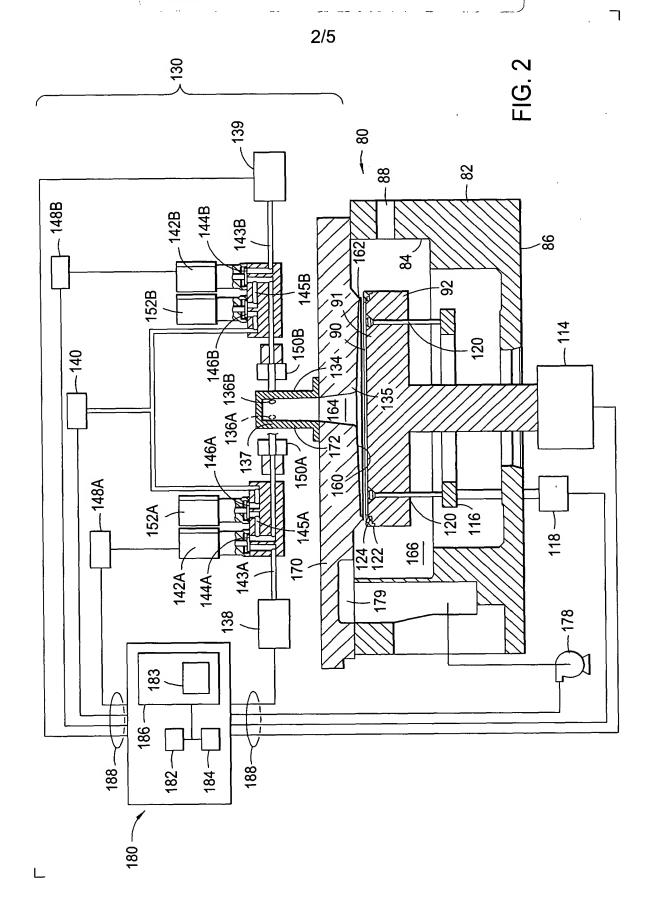
ATTY DKT. NO.: AMAT/5975.P1/CPI/COPPER/BG
U.S. SERIAL NO.: UNKNOWN CONF. NO.: UNKNOWN
FILED: HEREWITH
APPLICANT: APPLIED MATERIALS
TITLE: RUTHENIUM LAYER FORMATION FOR COPPER FILM DEPOSITION
INVENTOR: CHANG, ET AL.
EXPRESS MAIL NO.: EV351031212US PAGE 1 OF 5



ATTY DKT. NO.: AMAT/5975.P1/CPI/COPPER/BG
U.S. SERIAL NO.: UNKNOWN
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APPLICANT: APPLIED MATERIALS
TITLE: RUTHENIUM LAYER FORMATION FOR COPPER FILM DEPOSITION
INVENTOR: CHANG, ET AL.
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APPLICANT: APPLIED MATERIALS
TITLE: RUTHENIUM LAYER FORMATION FOR COPPER FILM DEPOSITION
INVENTOR: CHANG, ET AL.
EXPRESS MAIL No.: EV351031212US PAGE 3 OF 5

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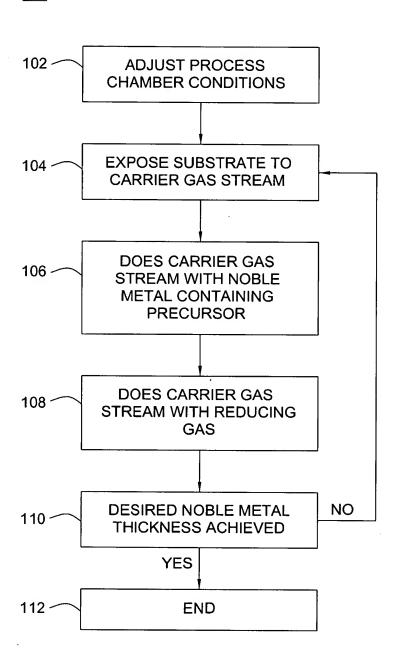
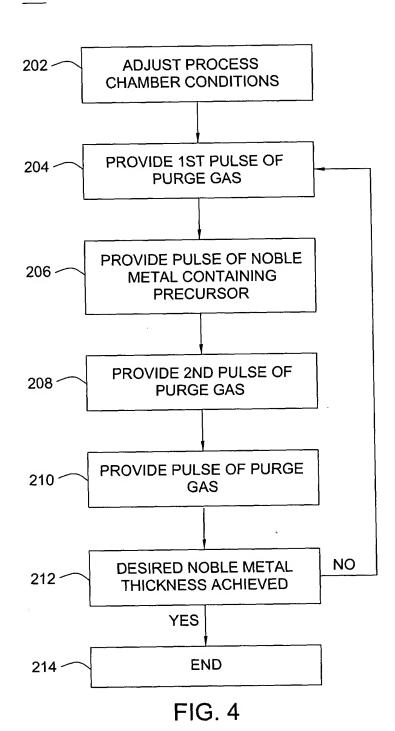


FIG. 3

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U.S. SERIAL NO.: UNKNOWN CONF. No.: UNKNOWN
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APPLICANT: APPLIED MATERIALS
TITLE: RUTHENIUM LAYER FORMATION FOR COPPER FILM DEPOSITION
INVENTOR: CHANG, ET AL.
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TITLE: RUTHENIUM LAYER FORMATION FOR COPPER FILM DEPOSITION
INVENTOR: CHANG, ET AL.

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INVENTOR: CHANG, ET AL.

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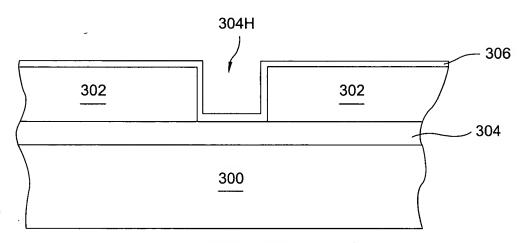


FIG. 5A

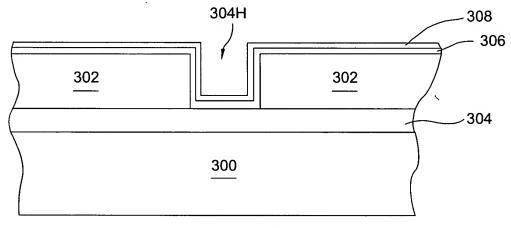


FIG. 5B

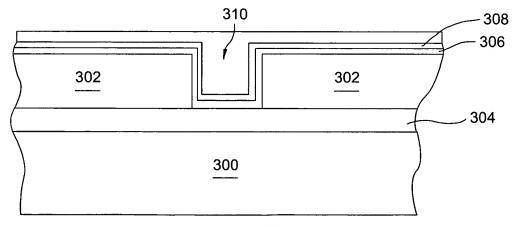


FIG. 5C